TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK3403

Switching Regulator Applications

Unit: mm

- Low drain-source ON resistance: RDS (ON) = 0.29Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 5.8 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = 100 \,\mu\text{A} \,(\text{max}) \,(V_{DSS} = 450 \,\text{V})$
- Enhancement-mode: $V_{th} = 3.0 \sim 5.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

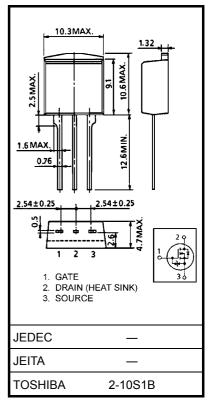
Characteristics		Symbol	Rating	Unit	
Drain-source voltage	;	V_{DSS}	450	V	
Drain-gate voltage (F	$R_{GS} = 20 \text{ k}\Omega$	V_{DGR}	450	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1) I _D	13	Α	
	Pulse (Note 1) I _{DP}	52	ı	
Drain power dissipat	ion (Tc = 25°C)	PD	100	W	
Single pulse avalance	the energy (Note 2) E _{AS}	350	mJ	
Avalanche current		I _{AR}	13	Α	
Repetitive avalanche	e energy (Note 3) E _{AR}	10	mJ	
Channel temperature	e	T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Thermal Characteristics

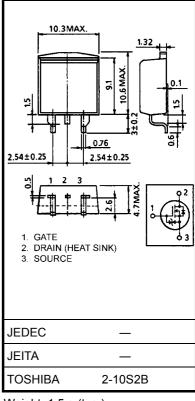
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.25	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

- Note 1: Please use device on condition that the channel temperature is below 150°C.
- Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 3.46 mH, $R_G = 25 \Omega$, $I_{AR} = 13 \text{ A}$
- Note 3: Repetitive rating; pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 1.5 g (typ.)



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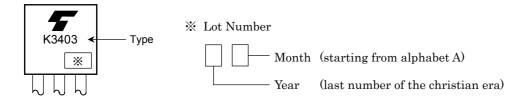
Electrical Characteristics (Tc = 25°C)

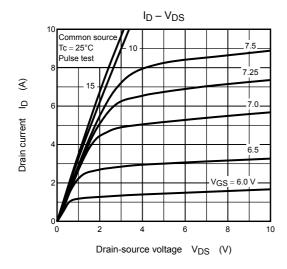
Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Gate-source brea	akdown voltage	V (BR) GSS	$I_G = 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off curr	ent	I _{DSS}	V _{DS} = 450 V, V _{GS} = 0 V	_	_	100	μА
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	450	_	_	V
Gate threshold ve	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	3.0	_	5.0	V
Drain-source ON	resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 6 A	_	0.29	0.4	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 6 A	3.0	5.8	_	S
Input capacitance	е	C _{iss}		_	1600	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	17	_	pF
Output capacitance		Coss		_	220	_	
Switching time	Rise time	t _r	V_{GS} 0 V V_{GS} 0 V 0	_	28		- ns
	Turn-on time	t _{on}		_	45	_	
	Fall time	t _f		_	10	_	
	Turn-off time	t _{off}		_	56	_	
Total gate charge		Qg		_	34	_	nC
Gate-source charge		Q _{gs}	$V_{DD} \simeq 360 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}$	_	19	_	
Gate-drain charge		Q _{gd}		_	15	_	

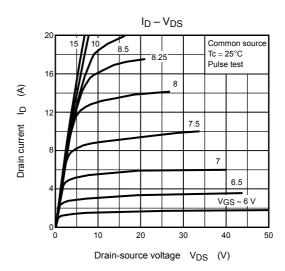
Source-Drain Ratings and Characteristics (Ta = 25°C)

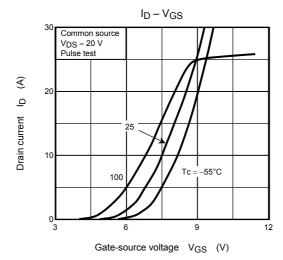
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	_	_	_	13	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	52	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 13 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 13 A, V _{GS} = 0 V,	_	300	_	ns
Reverse recovery charge	Qrr	dI _{DR} /dt = 100 A/μs	_	3.4	_	μС

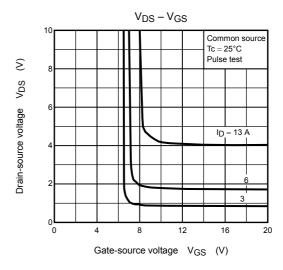
Marking

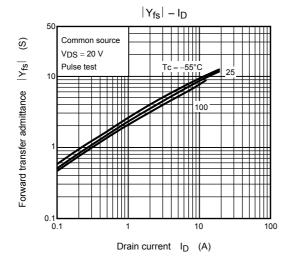


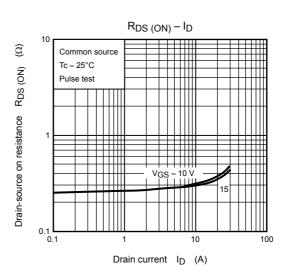




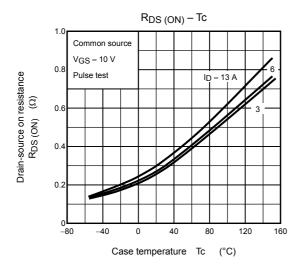


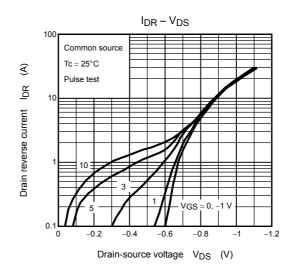


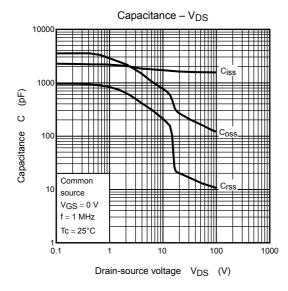


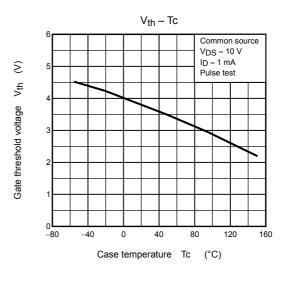


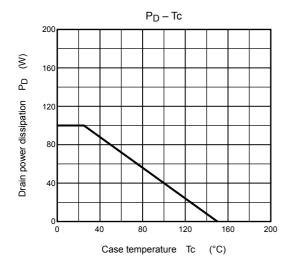
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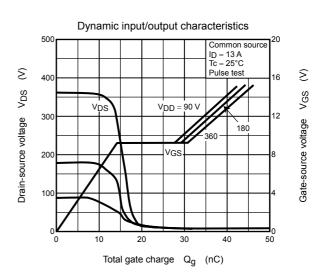


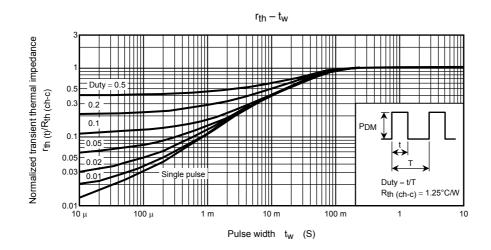


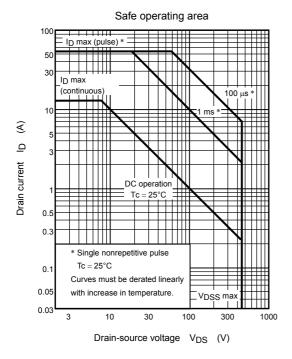


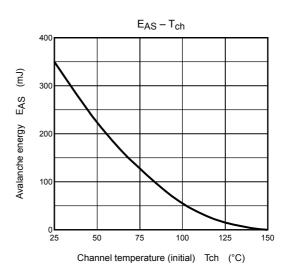


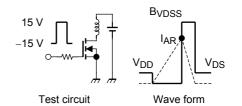












$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 3.46~mH \end{aligned} \qquad \text{EAS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{\text{BVDSS}}{\text{BVDSS} - \text{VDD}} \right)$$

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